



160V PNP SMALL SIGNAL TRANSISTOR IN SOT323

Features

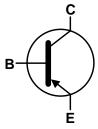
- **Epitaxial Planar Die Construction**
- Ultra-Small Surface Mount Package
- Complementary PNP Type: MMST5551
- Ideal for Low Power Amplification and Switching
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

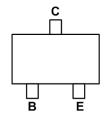
- Case: SOT323
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.006 grams (Approximate)







Device Symbol



Top View Pin-Out

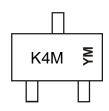
Ordering Information (Notes 4 & 5)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
MMST5401-7-F	AEC-Q101	K4M	7	8	3,000
MMST5401-13-F	AEC-Q101	K4M	13	8	10,000
MMST5401Q-7-F	Automotive	K4M	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to https://www.diodes.com/quality/
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



K4M = Product Type Marking Code YM = Date Code Marking Y or Y = Year (ex: F = 2018) M or \overline{M} = Month (ex: 3 = March)

Date Code Key

Year	2018	2019	20	20	2021	2022	2023	2024	20	25	2026	2027
Code	F	G	I	1	ı	J	K	L	1	M	N	0
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

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Absolute Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-160	V
Collector-Emitter Voltage	V _{CEO}	-150	V
Emitter-Base Voltage	V _{EBO}	-5	V
Continuous Collector Current	I _C	-200	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Power Dissipation	(Note 6)	P _D	200	mW
Thermal Resistance, Junction to Ambient (Note 6)		R _{θJA}	625	°C/W
Operating and Storage Temperature Range	$T_{J,}T_{STG}$	-55 to +150	°C	

ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 8)							
Collector-Base Breakdown Voltage	V_{CBO}	-160	_	V	$I_C = -100 \mu A, I_E = 0$		
Collector-Emitter Breakdown Voltage	V _{CEO}	-150	_	V	$I_C = -1 \text{mA}, I_B = 0$		
Emitter-Base Breakdown Voltage	V_{EBO}	-5	_	V	$I_E = -100 \mu A, I_C = 0$		
Collector Cutoff Current	I _{CBO}	_	-50	nA	$V_{CB} = -120V, I_E = 0$		
00.0000 00.000	·CBO			μΑ	$V_{CB} = -120V, I_E = 0, T_A = +100^{\circ}C$		
Emitter Cutoff Current	I _{EBO}	_	-50	nA	$V_{EB} = -3V, I_{C} = 0$		
ON CHARACTERISTICS (Note 8)					_		
DC Current Gain	h _{FE}	50 60 50	240 —	_	$\begin{split} I_C &= -1 mA \;,\; V_{CE} = -5 V \\ I_C &= -10 mA \;,\; V_{CE} = -5 V \\ I_C &= -50 mA \;,\; V_{CE} = -5 V \end{split}$		
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	-0.2 -0.5	V	$I_{C} = -10\text{mA}, I_{B} = -1\text{mA}$ $I_{C} = -50\text{mA}, I_{B} = -5\text{mA}$		
Base-Emitter Saturation Voltage	V _{BE(SAT)}	_	-1	V	$I_{C} = -10\text{mA}, I_{B} = -1\text{mA}$ $I_{C} = -50\text{mA}, I_{B} = -5\text{mA}$		
SMALL SIGNAL CHARACTERISTICS							
Output Capacitance	C _{obo}		6.0	pF	$V_{CB} = -10V$, $f = 1MHz$, $I_E = 0$		
Small Signal Current Gain	h _{fe}	40	260	_	V_{CE} = -10V, I_{C} = -1mA, f = 1kHz		
Current Gain-Bandwidth Product	f⊤	100	300	MHz	$V_{CE} = -10V, I_{C} = -10mA,$ f = 100MHz		
Noise Figure	NF	_	8	dB	V_{CE} = -5V, I_{C} = -200 μ A, R_{S} =10 Ω , f = 1kHz		

^{6.} For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.

7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

8. Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%.



Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

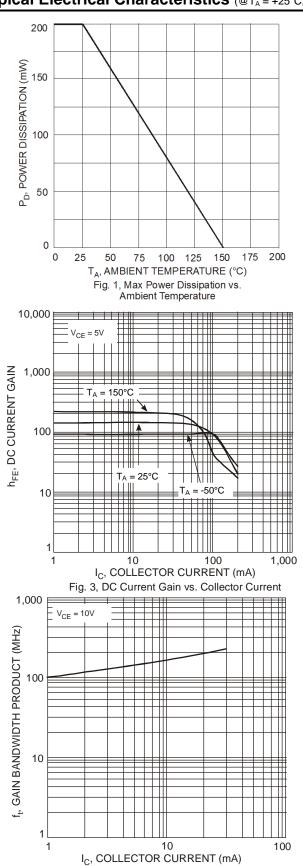
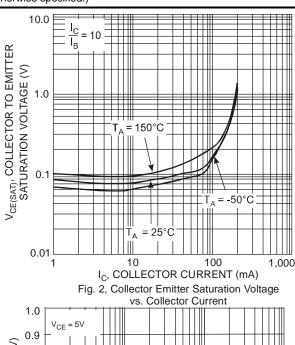


Fig. 5, Gain Bandwidth Product vs. Collector Current



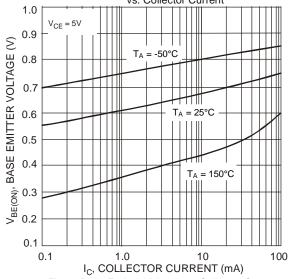


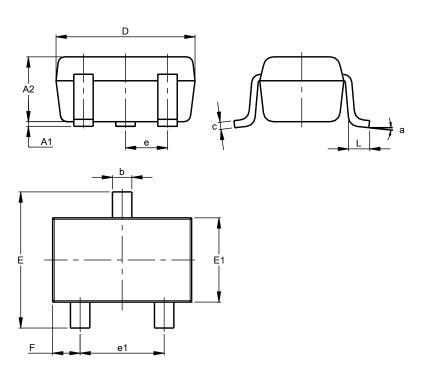
Fig. 4, Base Emitter Voltage vs. Collector Current



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT323

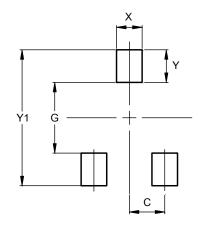


SOT323						
Dim	Min	Max	Тур			
A1	0.00	0.10	0.05			
A2	0.90	1.00	0.95			
b	0.25	0.40	0.30			
С	0.10	0.18	0.11			
D	1.80	2.20	2.15			
Е	2.00	2.20	2.10			
E1	1.15	1.35	1.30			
е	0.650 BSC					
e1	1.20	1.40	1.30			
F	0.375	0.475	0.425			
L	0.25	0.40	0.30			
а	0°	8°				
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT323



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.470
Y	0.600
Y1	2.500

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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